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Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 12/22

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EUROPÄISCHE NORM

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Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2022)

Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification de l'alimentation électrique par port USB (IEC 62680-1-2:2022)

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The text of document 100/3716/CDV, future edition 6 of IEC 62680-1-2, prepared by IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2022.

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IEC 62680-1-2

Edition 6.0 2022-09

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Interfaces de bus universel en série pour les données et l'alimentation électrique – Partie 1-2: Composants communs – Spécification de l'alimentation électrique par port USB

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

Part 1-2: Common components – USB Power Delivery specification

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The text of this International Standard is based on the following documents:

Draft	Report on voting
100/3716/CDV	100/3763/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

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Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
2.0	1.2	Including errata through 25-March-2016	25 March 2016
2.0	1.3	Including errata through 11-January-2017	11 January 2017
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.1	Including errata through 12-January-2016	12 January 2017
3.0	1.2	Including errata through 21-June-2018	21 June 2018
3.0	2.0	Including errata through 29-August-2019	29 August 2019
3.1	1.0	Including errata through May 2021	May 2021
3.1	1.1	Including errata through July 2021	July 2021

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1 Introduction

USB has evolved from a data interface capable of supplying limited power to a primary provider of power with a data interface. Today many devices charge or get their power from USB ports contained in laptops, cars, aircraft or even wall sockets. USB has become a ubiquitous power socket for many small devices such as cell phones, MP3 players and other hand-held devices. Users need USB to fulfill their requirements not only in terms of data but also to provide power to, or charge, their devices simply, often without the need to load a driver, in order to carry out “traditional” USB functions.

There are, however, still many devices which either require an additional power connection to the wall, or exceed the USB rated current in order to operate. Increasingly, international regulations require better energy management due to ecological and practical concerns relating to the availability of power. Regulations limit the amount of power available from the wall which has led to a pressing need to optimize power usage. The USB Power Delivery Specification has the potential to minimize waste as it becomes a standard for charging devices that are not satisfied by ***[USBBC 1.2]***.

Wider usage of wireless solutions is an attempt to remove data cabling but the need for “tethered” charging remains. In addition, industrial design requirements drive wired connectivity to do much more over the same connector.

USB Power Delivery is designed to enable the maximum functionality of USB by providing more flexible power delivery along with data over a single cable. Its aim is to operate with and build on the existing USB ecosystem; increasing power levels from existing USB standards, for example Battery Charging, enabling new higher power use cases such as USB powered Hard Disk Drives (HDDs) and printers.

With USB Power Delivery the power direction is no longer fixed. This enables the product with the power (Host or Peripheral) to provide the power. For example, a display with a supply from the wall can power, or charge, a laptop. Alternatively, USB power bricks or chargers are able to supply power to laptops and other battery powered devices through their, traditionally power providing, USB ports.

USB Power Delivery enables hubs to become the means to optimize power management across multiple peripherals by allowing each device to take only the power it requires, and to get more power when required for a given application. For example, battery powered devices can get increased charging current and then give it back temporarily when the user’s HDD requires spinning up. ***Optionally*** the hubs can communicate with the PC to enable even more intelligent and flexible management of power either automatically or with some level of user intervention.

USB Power Delivery allows Low Power cases such as headsets to negotiate for only the power they require. This provides a simple solution that enables USB devices to operate at their optimal power levels.

The Power Delivery Specification, in addition to providing mechanisms to negotiate power also can be used as a side-band channel for standard and vendor defined messaging. Power Delivery enables alternative modes of operation by providing the mechanisms to discover, enter and exit Alternate Modes. The specification also enables discovery of cable capabilities such as supported speeds and current levels.

1.1 Overview

This specification defines how USB Devices can negotiate for more current and/or higher or lower Voltages over the USB cable (using the USB Type-C® CC wire as the communications channel) than are defined in the ***[USB 2.0]***, ***[USB 3.2]***, ***[USB Type-C 2.0]*** or ***[USBBC 1.2]*** specifications. It allows Devices with greater power requirements than can be met with today’s specification to get the power they require to operate from V_{BUS} and negotiate with external power sources (e.g., Wall Warts). In addition, it allows a Source and Sink to swap power roles such that a Device could supply power to the Host. For example, a display could supply power to a notebook to charge its battery.